Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		**User Part Number**				
Nexperia B.V.		PESD3V3NW-SF				
Name of Laboratory		**Part Description**				
		NXP ICN8	Protection INDI			
Assembly reliability labs		BD package				
Test		**Test Conditions**	**Duration**	**# Lots**	**# Quantity**	**# Rejects**
# 1	**TEST** Pre- and Post-Stress Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below
# 5	**HTRB** High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	43	3440	0
# 7	**TC** Temperature Cycling	JESD22-A104 -40 °C to 125°C	1000 cycles	67	5360	0
# 8	**AC** Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	n.a.	n.a.	n.a.
# 9	**HAST** Highly Accelerated Stress Test	JESD22-A110 Tamb = 130 °C, RH = 85%, VR = 80 % of rated reverse voltage[1]	1000 hours	67	5360	0
# 10	**IOL** Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.
# 20	**RSH** Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.
# 21	**SD** Solderability	J-STD-002		12	120	0

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5)
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	**Technology**	**Quantity**	**Rejects**	**Failure Rate (FIT)**	**MTTF (hrs)**
NXP ICN8	Protection INDI	3440	0	1.2	8.10E+08